

Connector for Memory Stick Micro™

SCNA Series



Minimal mounting area for compact devices.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™



Combine Type

For W-SIM

Typical Specifications

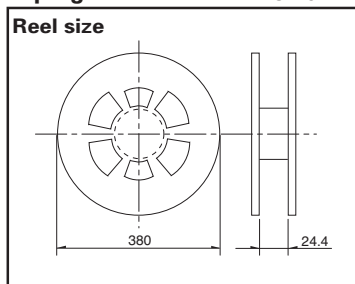
| Items | | Specifications |
|-------------|---------------------------------|-----------------------|
| Structure | Applicable media | Memory Stick Micro™ |
| | Mounting type | Surface mounting type |
| | Mounting style | Standard mount |
| | Media ejection structure | Push-push type |
| Performance | Operating temperature range | -40°C to +70°C |
| | Voltage proof | 250V AC 1minute |
| | Insulation resistance (Initial) | 1,000MΩ min. |
| | Contact resistance (Initial) | 100mΩ max. |
| | Insertion and removal cycle | 12,000cycles |

Product Line

| Media ejection structure | Mounting system | Stand-off (mm) | Packing system | Product No. |
|--------------------------|-----------------|----------------|----------------|-------------|
| Push-push type | Standard mount | 0 | Taping | SCNA1A0300 |

Packing Specifications

Taping Unit:mm



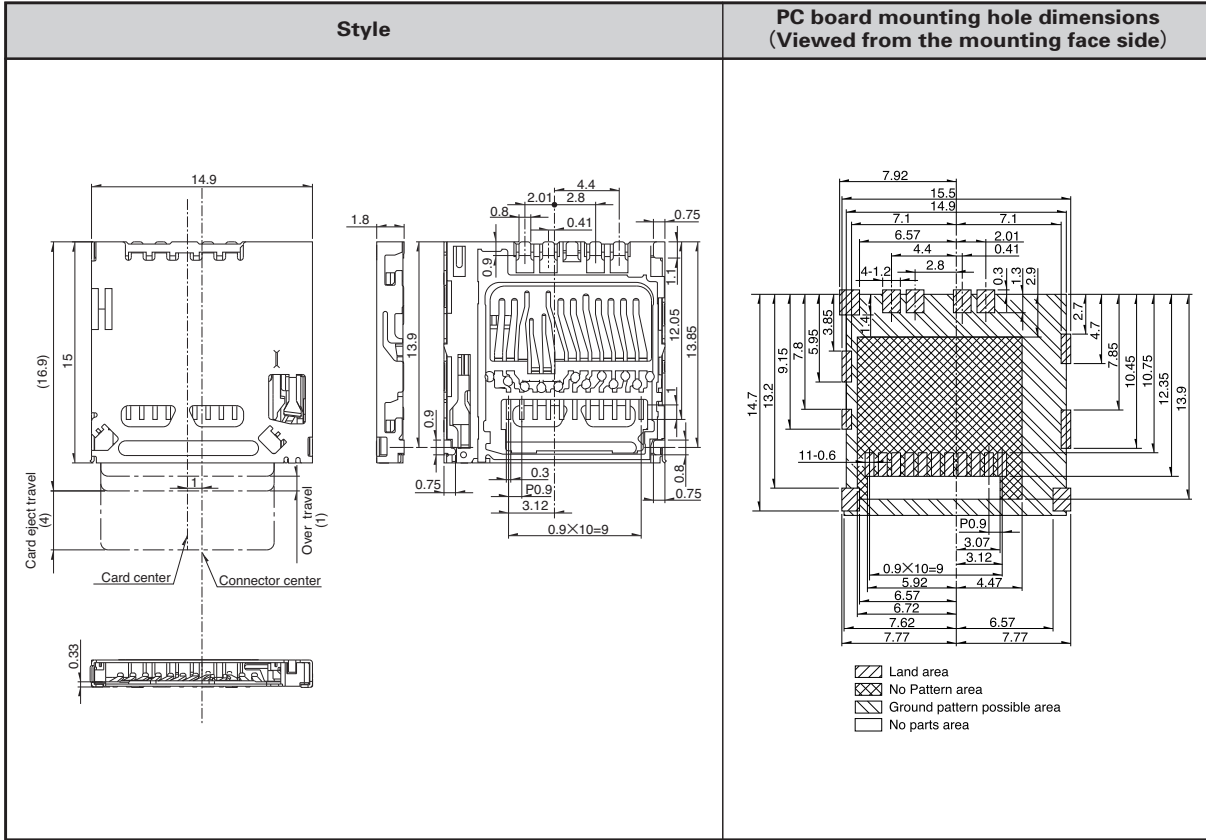
| Number of packages (pcs.) | | | Tape width (mm) | Export package measurements (mm) |
|---------------------------|---------------|------------------------|-----------------|----------------------------------|
| 1 reel | 1 case /Japan | 1 case /export packing | | |
| 1,500 | 4,500 | 9,000 | 24 | 403 × 403 × 249 |

Note

Please place purchase orders per minimum order unit N (integer).

Dimensions

Unit:mm



For SD Memory Card

For microSD™ Card


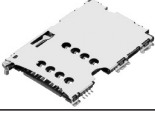



For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM

List of Varieties

| Applicable media | Product No. | Photo | Media ejection structure | Mounting style | Features | Stand-off (mm) | Auto motive use | Page | | |
|---------------------|--|---|--------------------------|---|------------------------------------|----------------|---------------------|------|---|-----|
| SIM Card 8pins | SCGC1B0101 |  | Push-push type | Standard mount | With switch | 0 | ○ | 541 | | |
| | SCGC1B0301 |  | | | With Automatic Locking Cam | | | | | |
| Memory Stick Micro™ | SCNA1A0300 |  | | | Without boss | | 543 | | | |
| Combine Type | SD Memory Card Multi-Media Card™ Memory Stick™ | SCDB3A0202 | | Push-push type | Reverse mount | | With boss | 0 | — | 545 |
| | | SCDB4A0101 | | | | | | | | |
| | SD Memory Card Multi-Media Card™ Multi-Media Card Plus™ Memory Stick™ xD-Picture Card™ | SCDG1A0101 | | | Standard mount | | | | | |
| | SCDG2A0101 | Reverse mount | | | | | | | | |
| | SD Memory Card Multi-Media Card™ Memory Stick™ xD-Picture Card™ | SCDG4B0100 | | Thin with a Thickness of 4.2mm | | | | | | |
| | microSD™ Card SIM Card 8pins | SCHG1B0100 | | Push-push type Manual insertion/removal | microSD™ Card right insertion type | | | | | 551 |
| W-SIM | SCZA1A0100 |  | | Push-push type | Standard mount | | Without boss L type | 0 | — | 553 |
| | SCZA1A0200 | | With boss L type | | | | | | | |
| | SCZA1A0300 | | Without boss 0.6mm type | | | | | | | |
| | SCZA1A0400 | | With boss 0.6mm type | | | | | | | |
| | SCZA1A0500 | | Without boss 1.2mm type | | | | | | | |
| | SCZA1A0600 | With boss 1.2mm type | | | | | | | | |
| | SCZA2A0100 |  | Manual insertion/removal | With boss L type | | | | | | |
| SCZA2A0200 | Without boss 0.6mm type | | | | | | | | | |

For SD Memory Card
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Note

○marks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

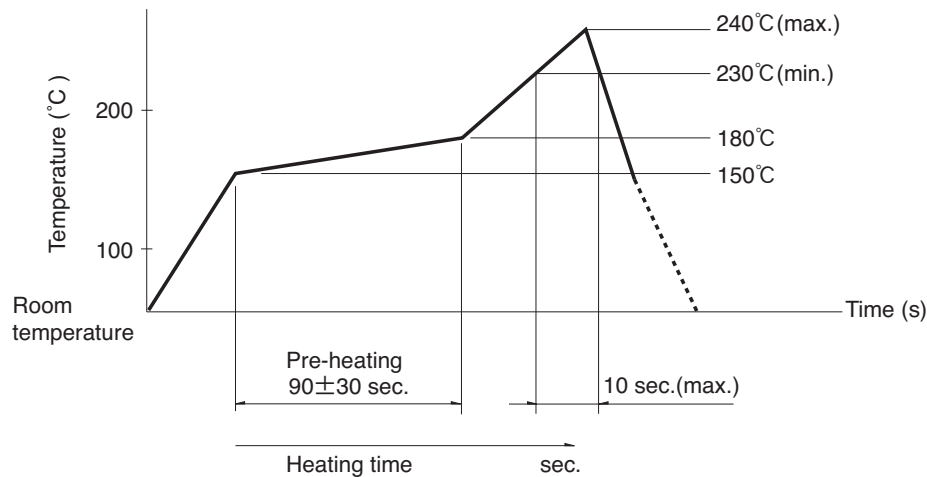
Note

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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



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Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

1.Connector handling precautions

- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.

If you wash it, it may cause deterioration of mechanically and electrically.

If washing is necessary, please make contact with us beforehand.

2.When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3.When soldering, do not use water soluble flux because this may corrode the product.

4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6.Please do not solder at the ejector pushing position.

7.To prevent contact disturbance by the sulfuration or oxidation of the contact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.

- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorine gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.

8.Don't push or hold down the metal cover of the connector, otherwise there is a possibility that the card would not be ejected or influences to other function.

9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.

- Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- Establish CR accumulation circuit.

10.This product does not operate normally when the card which does not conform to the specification is used occasionally.